

REMARKS

Rejections under 35 USC §103(a)

Claims 1, 2, 4, 5, 7-9 and 13-16 were rejected under 35 USC §103(a) as being unpatentable over Domae (US Publication Application No. 2002/0005584) in view of Vigna et al (U.S. Patent No. 6,605,873).

Claims 10-12 and 17-19 were rejected under 35 USC §103(a) as being unpatentable over Domae (US Publication Application No. 2002/0005584) in view of Vigna et al. (U.S. Patent No. 6,605,873) as applied to claim 1 above, and further in view of the Applicant's Prior Art Figures 1-4 (APAF).

Claim 1 has been amended to recite "wherein said first interlayer insulation film has a first Young modulus and said second interlayer insulation film has a second, larger Young modulus than said first Young modulus" incorporating the subject matter of original claim 10.

In rejecting claim 10, the examiner relied upon Figure 1. It is submitted, however, that Figure 1 of the present invention is not an Applicant's admitted prior art. They are "Related Art" but not a "Prior Art." Reference should be made to the Remarks filed on March 22, 2006.

Therefore, claim 1, as amended, patentably distinguish over the prior art. Claims 11-12 and 17-19 depend, directly or indirectly, from claim 1, which patentably distinguishes over the prior art as discussed above. Therefore, claims 11-12 and 17-19 patentably distinguish over the prior art for at least the same reasons.

NEW CLAIMS:

New claims 29 and 30 have been added. The new claims 29 and 30 are supported in the original disclosure, especially for example, Figure 5 and related description. More specifically,

Application No.: 10/780,701
Art Unit: 2815

Submission under 37 C.F.R. §1.114
Attorney Docket No.: 042113

Figure 5 shows the feature of the pillar including a Cu pattern 106P, a Cu plug 106p, a Cu pattern 107P and a Cu plug 107p aligned straight and extending straight from the device isolation region to the contact pad as set forth in new claim 29. According to the feature of new claim 29, it becomes possible to form the entire pillar concurrently with formation of the multilayer interconnection structure.

Furthermore, Figure 5 shows the feature of the pillar P100 including a plug 110p formed in the passivation film 110 in engagement with the bottom surface of the contact pad 111.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact the undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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